

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Takashi Moriguchi</td> <td>07/23/2012</td> </tr> <tr> <td>Masahiko Kobayakawa</td> <td>07/13/2012</td> </tr> </tbody> </table>		Name	Execution Date	Takashi Moriguchi	07/23/2012	Masahiko Kobayakawa	07/13/2012
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Takashi Moriguchi	07/23/2012						
Masahiko Kobayakawa	07/13/2012						
RECEIVING PARTY DATA							
Name:	Rohm Co., Ltd.						
Street Address:	21, Saiin Mizosakicho, Ukyo-ku						
City:	Kyoto						
State/Country:	JAPAN						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13554264</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13554264		
Property Type	Number						
Application Number:	13554264						
CORRESPONDENCE DATA							
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Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif							

CH \$40.00 13554264

Docket No.

**ASSIGNMENT OF PATENT APPLICATION**

WHEREAS,

1. **MORIGUCHI, Takashi** residing at **Kyoto, Japan** and a citizen of **Japan**
2. **KOBAYAKAWA, Masahiko** residing at **Kyoto, Japan** and a citizen of **Japan**

(hereinafter called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States for this invention which was filed on \_\_\_\_\_, entitled **LED MODULE AND LED MODULE MOUNTING STRUCTURE**, and which has been given application serial number \_\_\_\_\_ ;

and

WHEREAS **ROHM CO., LTD.** (hereinafter "ASSIGNEE") a corporation organized under the laws of **Japan** and having an office and place of business at **21, Sain Mizosakicho, Ukyo-ku, Kyoto, Japan** wishes to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign, and transfer to the ASSIGNEE, its successors, legal representative and assigns, the entire right, title and interest for the United States in and to the invention disclosed in said application, and in and to said application, as well as to all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents of the United States to issue all Letters Patent for said invention to the ASSIGNEE of the entire right, title and interest in and to the same, in accordance with the terms of this instrument.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEE) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEE, its successors and representatives all facts known to the UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEE, its successors or assigns, the entire right, title and interest in and to the said invention, patent applications, Letters Patent, rights, titles, benefits, privileges, and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represent and agree with said ASSIGNEE, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the

rights and property herein conveyed has been or will be made to others by the UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by the UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on the dates indicated below.

Takashi Moriyoshi  
1. Signature

23 July, 2012  
Date

Masahiko Kobayakawa  
2. Signature

13 July, 2012  
Date